

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
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Property Type	Number
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Total Attachments: 2	
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ASSIGNMENT

(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me, citizen of Japan,

by **Hitachi High-Technologies Corporation**, a corporation organized under the laws of **Japan**, located at **24-14, Nishi-Shimbashi 1-chome, Minato-ku, Tokyo, Japan**, receipt of which is hereby acknowledged I do hereby sell and assign to said **Hitachi High-Technologies Corporation**, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

ELECTRODE COVER FOR A PLASMA PROCESSING APPARATUS

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor,

Serial No. 29/610,996, filed on July 18, 2017,

executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said **Hitachi High-Technologies Corporation**, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said **Hitachi High-Technologies Corporation**.

,Signed on the date(s) indicated aside signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) Takamasa Ichino
Takamasa ICHINO

8/28/2017

2) Kohei Sato
Kohei SATO

8/28/2017

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

3)

Kazunori Nakamoto
Kazunori NAKAMOTO

8/28/2017